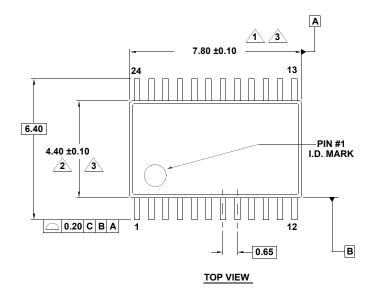
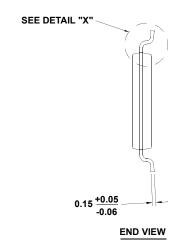
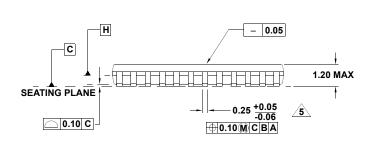
Package Outline Drawing

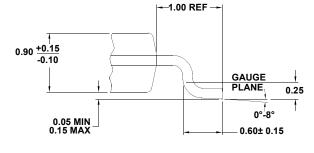
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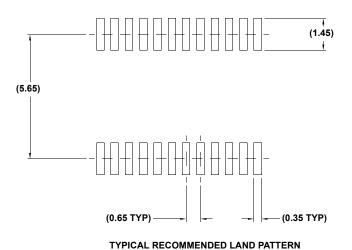






SIDE VIEW





NOTES:

1. Dimension does not include mold flash, protrusions or gate burrs.

Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.

DETAIL "X"

- <u>2.</u> Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.
- 3. Dimensions are measured at datum plane H.
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 5. Dimension does not include dambar protrusion. Allowable protrusion shall be 0.08mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- 6. Dimension in () are for reference only.
- 7. Conforms to JEDEC MO-153.

